ABSTRACT OF THE DISCLOSURE

An apparatus that inspects wire breaking of a semiconductor integrated circuit includes a voltage applying device (12), a light pulse source (14), a scanning device (16), an electromagnetic wave detection device (18), and a wire breaking detection device (20). The voltage applying device (12) maintains a semiconductor integrated circuit in a state where a predetermined voltage is being applied thereto. The light pulse source (14) generates an ultrashort light pulse (2). The scanning device (16) two-dimensionally scans and irradiates the two-dimensional circuit of the semiconductor integrated circuit by using the ultrashort light pulse (2). The electromagnetic wave detection device (18) detects an electromagnetic wave (3) radiated from a position irradiated with the ultrashort light pulse on the semiconductor integrated circuit. The wire breaking detection device (20) detects wire breaking of the irradiated position based on presence and absence or intensity of the electromagnetic wave.